

BOARD LEVEL COOLING – Extruded 5000

Extruded 5000 is a series of dual radial board level heat sinks designed to cool TO-218, TO-220, and TO-247 devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
513001B02500G	TO-218, TO-247
513002B02500G	TO-220
513002B32500G	TO-220
513102B02500G	TO-220
513201B02500G	TO-218
513202B02500G	TO-220
513301B02500G	TO-218, TO-247



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Screw & Nut, Mounting Kit
Board Attachment Options	Solderable Pins
Thermal Interface Material	-
Heat Sink Mounting Direction	Horizontal, Vertical

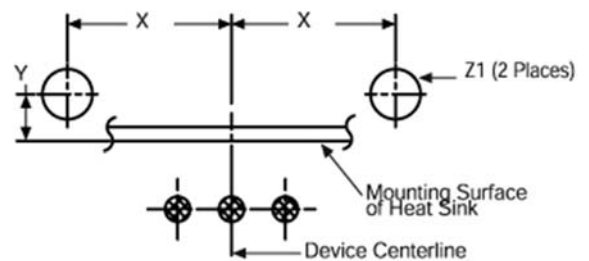
Property	Details
Heat Sink Length (mm)	12.70
Heat Sink Width (mm)	34.92
Heat Sink Height (mm)	See Dim "A" Below
X Dimension (mm)	12.70
Y Dimension (mm)	0.79
Z Dimension (mm)	2.67

MECHANICAL & PERFORMANCE

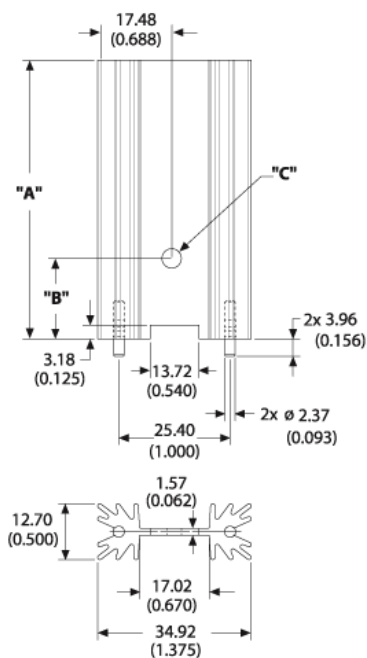
Drawing dimensions are shown in mm, (in)

Part Number	"A" Dim	"B" Dim	"C" Dim
513001B02500G	25.40	21.59	3.66
513002B02500G	25.40	18.29	3.18
513002B32500G	25.40	-	-
513102B02500G	38.10	18.29	3.18
513201B02500G	12.70	-	-
513202B02500G	50.80	18.29	3.18
513301B02500G	63.50	21.59	3.66

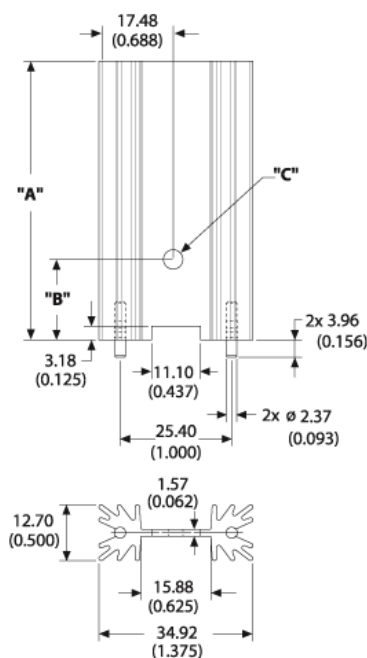
Mounting Details:



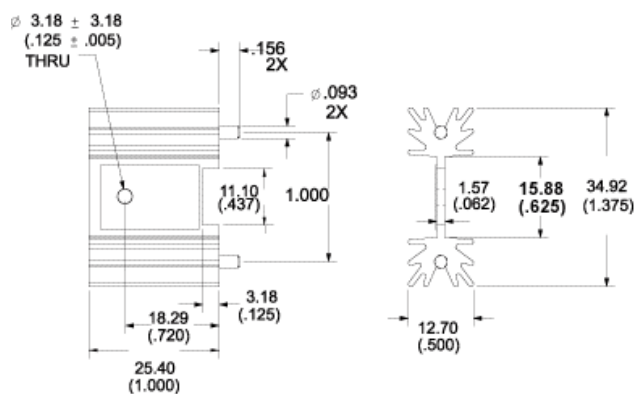
Part Numbers: 513001B02500G,
513201B02500G, 513301B02500G



Part Numbers: 513002B02500G,
513102B02500G, 513202B02500G



Part Number: 513002B32500G



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